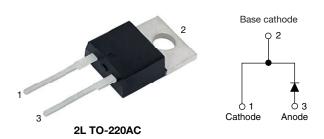
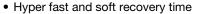


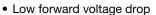
Hyperfast Rectifier, 30 A FRED Pt®

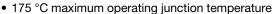


PRIMARY CHARACTERISTICS					
I _{F(AV)}	30 A				
V_{R}	650 V				
V _F at I _F at 125 °C	1.6 V				
t _{rr}	27 ns				
T _J max.	175 °C				
Package	2L TO-220AC				
Circuit configuration	Single				

FEATURES









• True 2 pin package

AEC-Q101 qualified

· Material categorization:

definitions compliance

www.vishay.com/doc?99912

FREE

RoHS
COMPLIANT
HALOGEN

please see

DESCRIPTION / APPLICATIONS

Ultra low V_F, soft-switching hyper fast rectifiers optimized for discontinuous (critical) mode (DCM) power factor correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Repetitive peak reverse voltage	V_{RRM}		650	V	
Average rectified forward current	I _{F(AV)}	T _C = 120 °C	30	•	
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	210	A	
Operating junction and storage temperature	T _J , T _{Stg}		-55 to +175	°C	

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS MIN. TYP.			MAX.	UNITS	
Breakdown voltage, blocking voltage	$V_{BR}, \ V_{R}$	I _R = 250 μA	650	-	-		
Forward voltage	V _F	I _F = 30 A - 2.1		2.5	V		
		$I_F = 30 \text{ A}, T_J = 125 ^{\circ}\text{C}$	-	1.6	1.7		
Davoras laglaga aurrent	_	$V_R = V_R$ rated	-	0.02	30		
Reverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	50	300	HA μΑ	
Junction capacitance	C _T	V _R = 200 V	-	22	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH	



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
Reverse recovery time	t _{rr}	T _J = 25 °C	I _F = 1 A dI _F /dt = 100 A/μs V _R = 30 V	-	35	-	- ns	
		T _J = 25 °C	$I_F = 30 \text{ A}$ $dI_F/dt = 1000 \text{ A/}\mu\text{s}$ $V_R = 400 \text{ V}$	-	27	-	115	
		T _J = 125 °C		-	88	=		
Dook recovery current	I _{RRM}	T _J = 25 °C		-	15	-	Α	
Peak recovery current		T _J = 125 °C		-	24	-	_ ^	
Reverse recovery charge	Q _{rr}	T _J = 25 °C] ''	-	330	=	200	
		T _J = 125 °C		-	1350	-	nC	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Thermal resistance, junction to case	R _{thJC}		-	1.0	1.3		
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	70	°C/W	
Thermal resistance, case to heat sink R _{thCS} Mounting surface, flat, smooth, and greased		-	-	0.5			
Weight			-	0.2	=	g	
weignt			-	0.07	-	oz.	
Mounting torque			6.0		12	kgf · cm	
Mounting torque			(5.0)	-	(10)	(lbf \cdot in)	
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C	
Marking device		Case style: 2L TO-220AC	ETX3007TH				

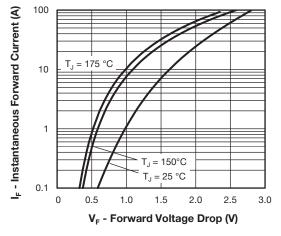


Fig. 1 - Typical Forward Voltage Drop Characteristics

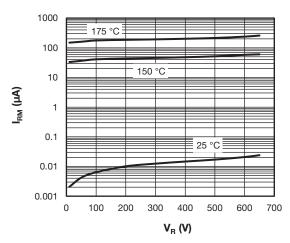


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

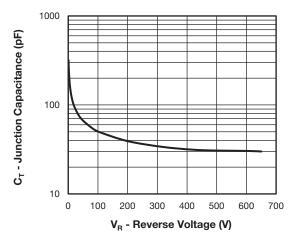


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

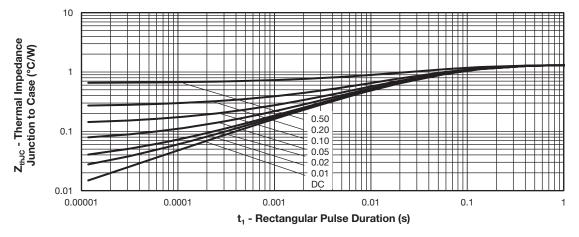


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

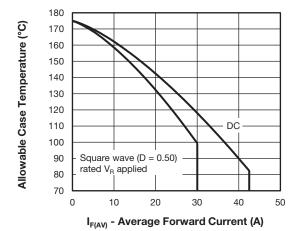


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

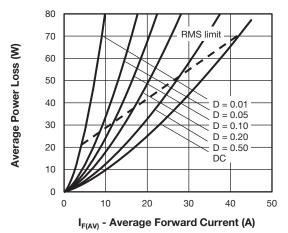
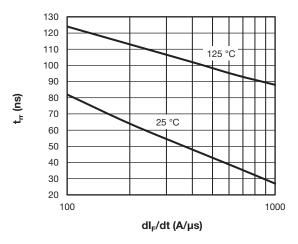


Fig. 6 - Forward Power Loss Characteristics

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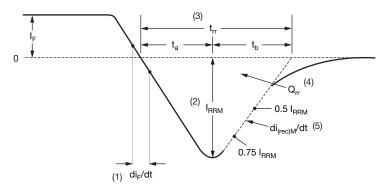
Vishay Semiconductors



1400
1200
1000
1000
125 °C
25 °C
1000
1000
1000
1000
1000

Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

Fig. 8 - Typical Reverse Recovery Time vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

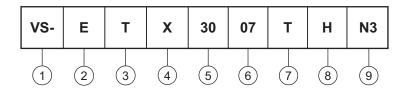
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - E = single diode

3 - Package:

T = TO-220

4 - X = hyper fast recovery

5 - Current rating (30 = 30 A)

6 - Voltage rating (07 = 650 V)

7 - T = True 2 pin TO-220

8 - H = AEC-Q101 qualified

9 - Environmental digit:

N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

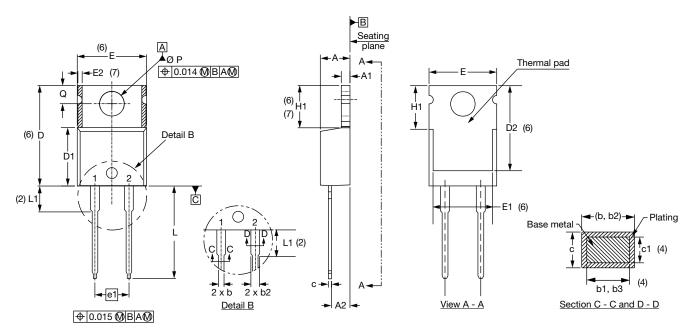
ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-ETX3007THN3	50	1000	Antistatic plastic tube				

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?96069				
Part marking information	www.vishay.com/doc?95391				
SPICE model	www.vishay.com/doc?96532				



TO-220AC 2L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INCHES MIN. MAX.		NOTES
STIVIBUL	MIN.	MAX.			NOTES
А	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
С	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6
Е	10.11	10.51	0.398	0.414	3, 6

SYMBOL	MILLIN	IETERS	INCHES		NOTES
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOIES
E1	6.86	8.89	0.270	0.350	6
E2	-	0.76	-	0.030	7
e1	4.88	5.28	0.192	0.208	
H1	5.84	6.86	0.230	0.270	6, 7
L	13.52	14.02	0.532	0.552	
L1	3.32	3.82	0.131	0.150	2
ØΡ	3.54	3.73	0.139	0.147	
Q	2.60	3.00	0.102	0.118	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- $^{(7)}$ Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC® TO-220, except D2, where JEDEC® minimum is 0.480"



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